Datacon 2200 evo ^{advanced}

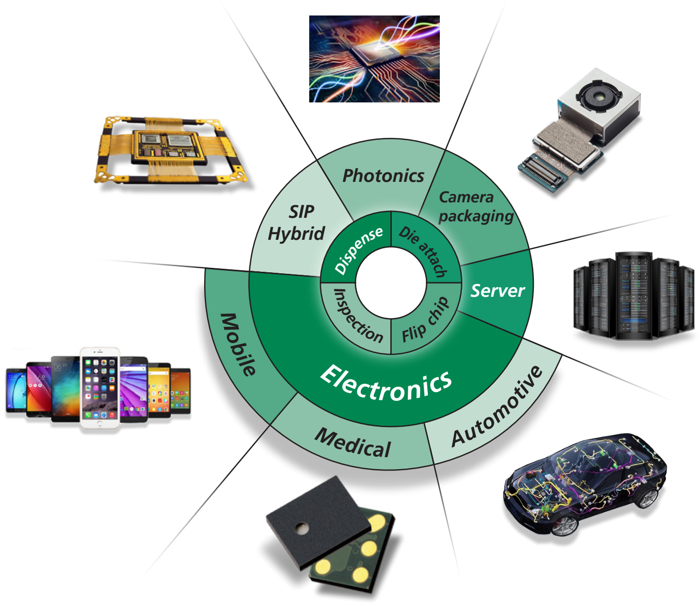
Accuracy & Flexibility for your mass production

The new Datacon 2200 evo ^{advanced} is the latest edition in the well-established and field proven Multi Module Attach platform of Besi.

With an all new gantry & controller system as well as a completely new vision and camera generation Datacon 2200 evo ^{advanced} offers superb 3µm placement accuracy while still focusing on your productivity and throughput requirements.

While significantly increasing the accuracy and placement capabilities the Datacon 2200 evo ^{advanced} does not forget its roots in the Multi Module Attach family. It is still offering the unbeaten flexibility as well as the full customization capability that the Datacon 2200 evo platform is so well known for.

Future Proof Equipment



3µm @ 3s !


NEW GUI

3µm

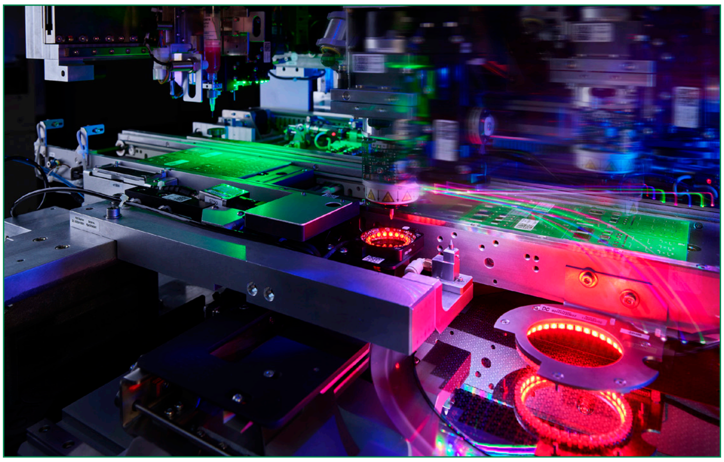
FLEXIBILITY

UV CURING

MULTI CHIP

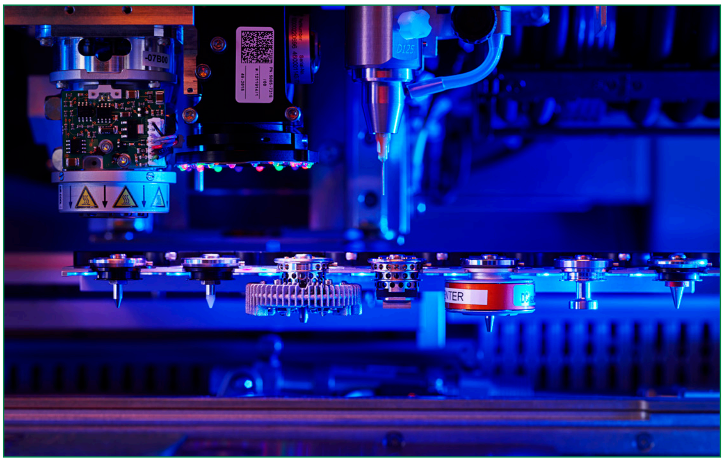
T2T

www.besi.com



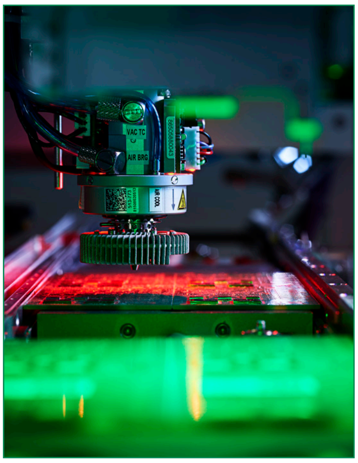
Accuracy

- ± 3 μm @ 3s placement accuracy
- ± 0.07° @ 3s rotational accuracy
- New vision, optics and camera system
- Various configurable (FOV & resolution) set of cameras
- 3D & contactless height measurement options



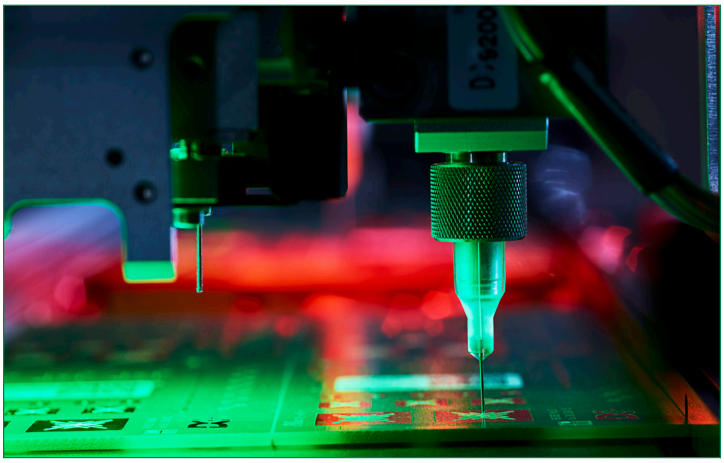
Multi Chip

- Max. 14 different pick up tools/nozzles
- 5 eject tools
- 3 different epoxies/adhesives in a single pass
- Any flip chip / face up die combination
- Dual module for even higher productivity (option)



Bonding

- 0.5 - 25 N closed loop bond-force
- 0 – 360° bond rotation
- Heated bond head (max. 450 °C) (option)
- UV curing with up to 2000 mW/cm^2 (365/405 nm) (option)



Dispensing

- High end auger pump
- Time pressure dispensing
- Piezo jetter valves
- Pin transfer
- Auto epoxy volume control

Machine Performance

- x/y placement ± 3 μm @ 3s
- Theta accuracy ± 0.07° @ 3s
- 0 – 360° rotation
- ≤ 450 °C bond head heating
- ≤ 150 °C bond insert heating
- In situ UV curing option
- 3/5/12 MPix cameras
- 1.8 – 12 mm FOV

Substrates

- 13”x 8” max. working area
- FR4, lead-frame, strips, carrier, boat, ceramics, wafer

Components

- size: 0.17 mm – 30 mm
- thickness: 0.05 mm – 17 mm
- wafer, waffle-pack, gel-pack, feeder, tray

Machine

- W x D x H: 1160 x 1225 x 1800 mm
- Weight: ± 1450 kg /module
- 3 x 400 VAC | 50/60 Hz | 2.3 kVA
- 6.0 bar CDA
- -0.8 bar vacuum
- 18 – 22 °C ambient temperature